

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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QSBT40

QUAD DATA LINE SCHOTTKY BUS TERMINATOR

Features

- Low Forward Voltage Drop
- Fast Switching
- Very High Density
- Ultra-Small Surface Mount Package PN Junction Guard Ring for Transient and ESD Protection
- Provide Transient Protection for High-Speed Data Lines in Accordance With: IEC61000-4-2 (ESD) 15kV (Air), 8kV (Contact)
- IEC61000-4-4 (EFT) 80A (tp = 5/50 ns) IEC61000-4-5 (Lightning) Class 3
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
 Halogen and Antimony Free. "Green" Device (Notes 3 & 4)

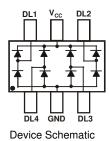
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)





Top View



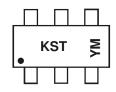
Ordering Information (Note 5)

Part Number	Case	Packaging
QSBT40-7-F	SOT363	3000/Tape & Reel
QSBT40-13-F	SOT363	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
- 5. For packaging details, go to our website at http://www.diodes.com.

Marking Information



KST = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002)

M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004		2011	2012	2013	2014	2015	2016	2017
Code	М	N	Р	R		Υ	Z	Α	В	С	D	Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _R WM V _R	30	V
Forward Continuous Current (Note 6)	I _{FM}	200	mA
Non-Repetitive Peak Forward Surge Current @ t < 1.0s	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	625	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-65 to +125	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	30			٧	$I_R = 100 \mu A$
Forward Voltage	V _F	_	l	280 350 450 550 1000	mV	$\begin{split} I_F &= 0.1 \text{mA, tp} < 300 \mu \text{S} \\ I_F &= 1.0 \text{mA, tp} < 300 \mu \text{S} \\ I_F &= 10 \text{mA, tp} < 300 \mu \text{S} \\ I_F &= 30 \text{mA, tp} < 300 \mu \text{S} \\ I_F &= 100 \text{mA, tp} < 300 \mu \text{S} \end{split}$
Reverse Current (Note 7)	I_R	_		2	μΑ	$V_R = 25V$
Total Capacitance	Ст	_	10.0 6.5		pF	$V_R = 0$, $f = 1.0MHz$ (Note 8) $V_R = 0$, $f = 1.0MH_z$ (Note 9)
Reverse Recovery Time	t _{rr}	_		5.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$

Notes:

- 6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. At $V_R = 0V$, DL(X) to V_{CC} or GND.
- 9. At $V_R = 0V$, between Data Lines (e.g., DL1 and DL4).

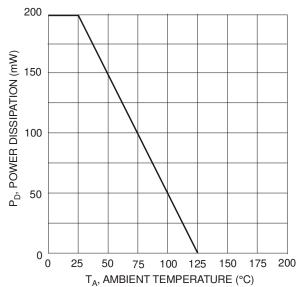
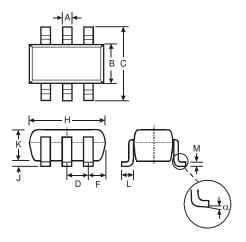


Fig. 1 Max Power Dissipation vs. Ambient Temperature



Package Outline Dimensions

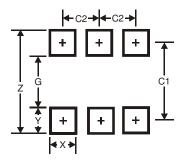
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT363						
Dim	Min	Max	Тур			
Α	0.10	0.30	0.25			
В	1.15	1.35	1.30			
C	2.00	2.20	2.10			
D	0.65 Typ					
F	0.40	0.45	0.425			
Н	1.80	2.20	2.15			
7	0	0.10	0.05			
K	0.90	1.00	1.00			
L	0.25	0.40	0.30			
М	0.10	0.22	0.11			
α	0°	8°	-			
All Dimensions in mm						

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
C1	1.9
C2	0.65



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 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
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